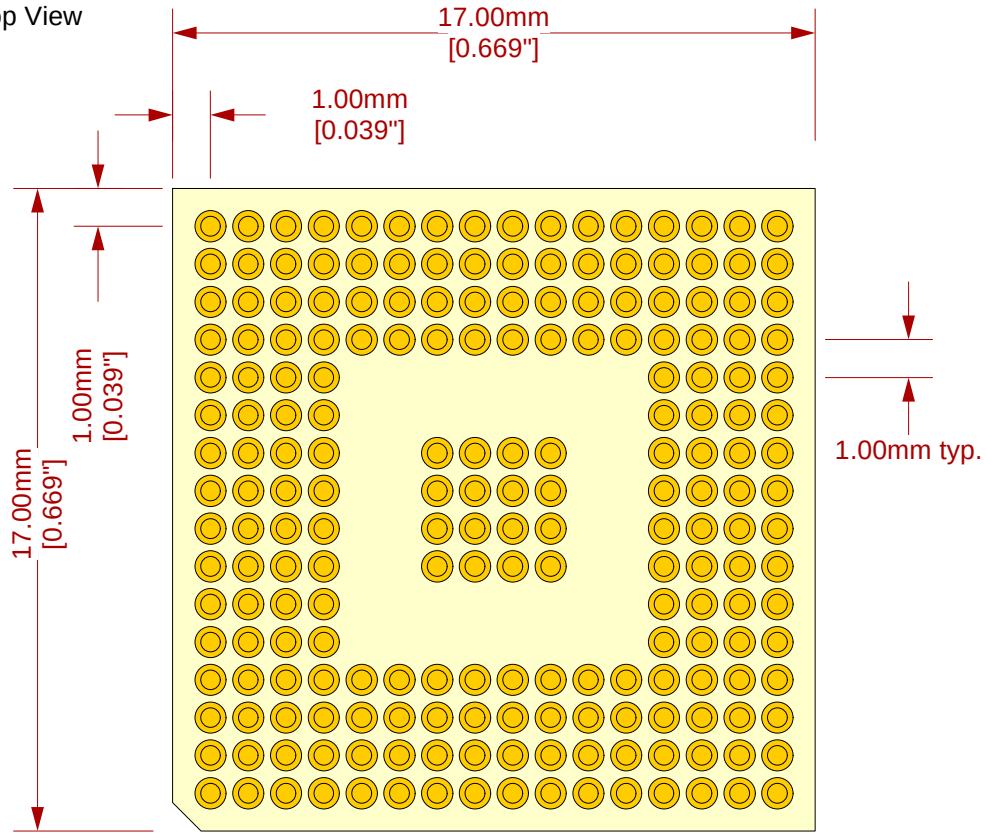
Patent Pending

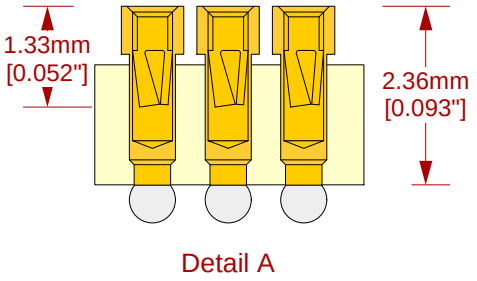
Top View



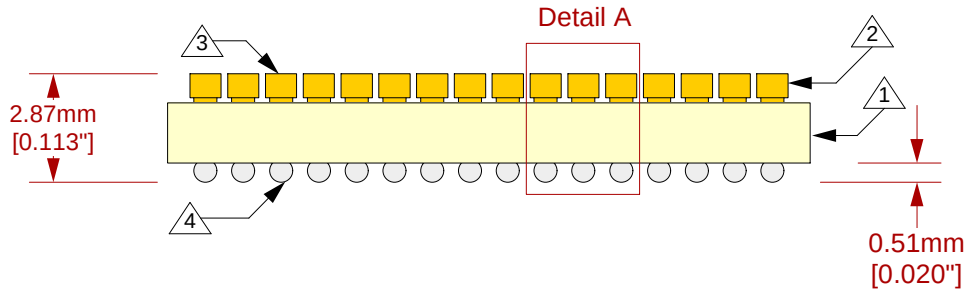
Ordering Information:

Solder Ball Alloy	Part Number Suffix
Sn63Pb37	-42
Sn96.5Ag3.0Cu0.5	-42F*

*RoHS Compliant



Side View



CONTACT DATA
Accepts 0.20mm - 0.33mm Diameter pins
3-finger
37/25 gram, Initial insertion force (with 0.254mm/0.203mm dia. pin)
30/22 gram, normal force (with 0.254mm/0.203mm dia. pin)
20/17 gram, extraction force (with 0.254mm0.203mm dia. pin)

1. Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. (RoHS)
2. Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
3. Contacts: Beryllium Copper Alloy172, HT; Finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
4. Solder Balls (See table above)

Description: Giga-snaP BGA SMT Foot
208 position (1.0mm pitch) gold plated female receptacle pins to SMT solder balls (BGA type). Pin asignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.18mm [±0.007"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA208C-B-42(F) Drawing	Status: Released	Scale: 5:1	Rev: C
 PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: B Fedde	Date: 8/23/04	
	File: SF-BGA208C-B-42 Dwg	Modified:1/6/06	